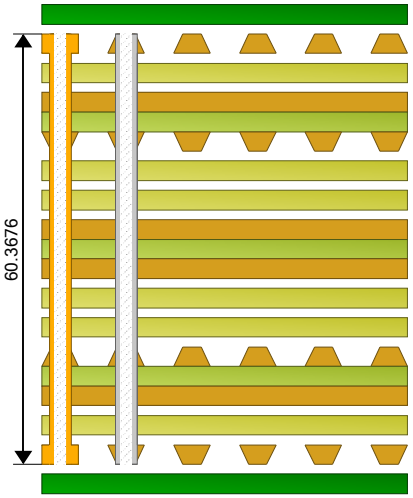
Layer	Stack up	Description	Base Thickness	Finish Thickness	Isolation Distance	Copper Coverage	εr
		Taiyo PSR 2000					4.000
1		Copper Foil 12 microns	0.394	1.673		100.000	
		EM827B Prepreg 2113	4.850	3.850	3.346		3.870
2			1.260	1.260		60.000	
		EM827 8 mil core 1/1	8.000	8.000	8.000		4.040
3			1.260	1.260		30.000	
		EM827B Prepreg 2113	4.850	3.850	3.133		3.870
		EM827B Prepreg 2113	4.850	3.850	3.133		3.870
4			1.378	1.378		60.000	
		EM827 14 mil core 1/1	14.000	14.000	14.000		4.280
5			1.378	1.378		60.000	
		EM827B Prepreg 2113	4.850	3.850	3.133		3.870
		EM827B Prepreg 2113	4.850	3.850	3.133		3.870
6			1.260	1.260		30.000	
		EM827 8 mil core 1/1	8.000	8.000	8.000		4.040
7			1.260	1.260		60.000	
		EM827B Prepreg 2113	4.850	3.850	3.346		3.870
8		Copper Foil 12 microns	0.394	1.673		100.000	
		Taiyo PSR 2000					4.000

Copper Thickness = 11.142 |Dielectric Thickness = 49.226 |Overall Processed Thickness = 60.368 |

Impedance ID	Structure Name	Impedance Signal Layer	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width	Upper Trace Width	Trace Separation	Lower Ground Strip Width	Upper Ground Strip Width	Ground Strip Separation	Broadside 2nd Layer	Trace Offset	Calculated Impedance	Target Impedance
1	Edge Coupled Coated Microstrip 1B	1	2	0	4.067	3.067	7.923	0.000	0.000	0.000	0	0.000	99.990	100.000
2	Edge Coupled Offset Stripline 1B1A	3	2	4	4.772	3.772	7.988	0.000	0.000	0.000	0	0.000	100.010	100.000
3	Edge Coupled Offset Stripline 1B1A	6	5	7	4.714	3.714	7.776	0.000	0.000	0.000	0	0.000	100.000	100.000
4	Edge Coupled Coated Microstrip 1B	8	7	0	4.067	3.067	7.923	0.000	0.000	0.000	0	0.000	99.990	100.000

Notes

StackName: Master	Version:	Revision:	Modification:	Date of Revision:	Editor		
Date:	Associated Documents:					Page 1/1	
Author:							
Department:							
Site:							